

Technical Bulletin

Delta DSP 718D SAC305 Solder Paste

DESCRIPTION

Delta® DSP 718D is a water soluble, halogen free, dispensing paste designed specifically for high temperature lead free alloys, such as SAC alloys. It provides the fluxing activity levels that promote thermal stability and prevents thermal degradation when reflowing under air atmosphere (normal). DSP 718D yields bright, shiny joints post-reflow and is easily dispensed from the syringe. It is available in 10cc or 30 cc syringes.

FEATURES & BENEFITS

- Low foaming
- Yields bright, shiny joints
- Excellent wettability
- Easily dispensed

TECHNICAL SPECIFICATIONS

	Specification	Test Method
Flux Classification	ORH0	IPC-J-STD-004B
Copper Mirror	>50% removal of copper film	IPC-TM-650 2.3.32
Corrosion (Cleaned)	Pass	IPC-TM-650 2.6.15
SIR (Cleaned)	4.55 x 1010 ohms	IPC-TM-650 2.6.3.3
Post Reflow Flux Residue	60%	TGA Analysis
Acid Value	55	IPC-TM-650 2.3.13
Metal Loading	87%	IPC-TM-650 2.2.20
Viscosity		
Brookfield (1), kcps	400+/-10% kcps	IPC-TM-650 2.4.34 modified
Malcom (2), poise	850-1100	IPC-TM-650 2.4.34.3 modified
Thixotropic Index	0.50-0.60	
Slump Test	Pass	IPC-TM-650 2.4.35
Solder Ball Test	Pass	IPC-TM-650 2.4.43
Tack		
Initial	96 gm	JIS Z 3284
Tack retention @ 24 hr	127gm	JIS Z 3284

HANDLING & STORAGE

It is recommended that solder paste be stored at a temperature of between 35-50 F (2-10 C) to minimize solvent evaporation, flux separation, and chemical activity. If room temperature storage is necessary it should be maintain between 68-77F (20-25 C) .

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SOLDER COMPOSITION

Sn/Ag/Cu (Tin/Silver/Copper) alloys are designed as a lead-free alternative for Sn/Pb alloys for electronics assembly operations. Sn/Ag/Cu alloys conform and exceed the impurity requirements of J-STD-006 and all other relevant international standards.

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Typical Analysis														
	Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
LF955-38	Bal	3.6-4.0	0.5-0.9	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
LF958-35	Bal	3.3-3.7	0.5-0.9	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
LF965-30	Bal	2.8-3.2	0.3-0.7	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
LF217	Bal	3.8-4.2	0.3-0.7	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

PARTICLE SIZE

Sn/Ag/Cu alloys are available in 3(45-25µm), 4(38-20µm), and 5 (25-15µm) J-STD-005 powder distribution. Solder powder distribution is measured utilizing laser diffraction, optical analysis and sieve analysis. Careful control of solder powder manufacturing processes ensures the particles' shape are 95% spherical minimum (aspect ratio < 1.5) and that the alloy contains a typical maximum oxide level of 100 ppm.

METAL LOADING

Typical metal loading for dispensing application is 86-87 %. Compared to typical Sn63/Sn62 solder pastes manufactured with 88% by weight metal loading, DSP 718D Lead Free provides as much as 10-12% higher metal volume than Sn63/Sn62 alloys.

SOLDER PASTE PRINTING - DISPENSING

Needle Gauge	Needle inner diameter		Applicable powder
	in.	µm	(mesh cut)
18	0.033	838	-200+325
20	0.023	584	-325+500
21	0.020	508	-325+500
22	0.016	406	-325+500
23	0.013	330	-325+500
25	0.010	254	-400+635
27	0.008	203	-500

The clearance gap between the needle and the substrate affects the shape and quality of the dot dispensed. If the clearance is too little, the dot tends to be flattened out, and if too large, the dot tends to have long tailing.

SOLDER PASTE PRINTING - PRESSURE

The pressure applied in the syringe should be kept at a minimum, and the proper head pressure kept in the range of 15-25 lb/in² (1.05-1.76 kg/cm²). In cases where a paste requires much higher pressure (more than 40 lb/in² or 2.82 kg/cm²) to dispense, the paste will become inconsistent and clogging may be expected. The external air pressure supply should be maintained constant.

SOLDER PASTE PRINTING - OPEN & ABANDON TIME

Tests have proven that DSP 718D will perform during continuous dispensing for up to 8 hrs. The paste can be left in the dispensing unit for up to 4 hours without paste drying out. If extended downtime is expected (>4 hrs) , the whole dispensing system should be flushed without leaving any paste in any part of the system.

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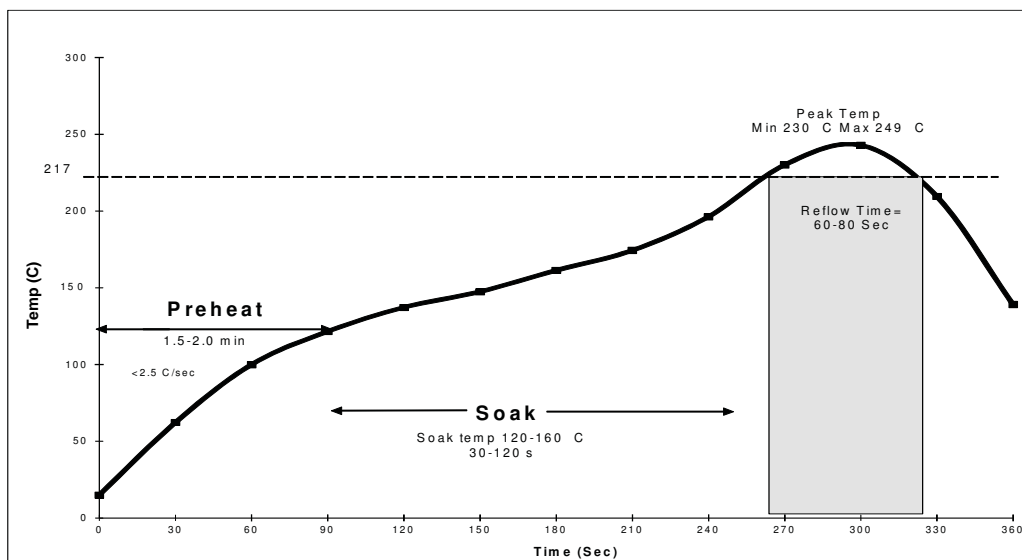
SOLDER PASTE PRINTING - PASTE APPLICATION

Solder paste should be taken out of the refrigerator at least 3 to 6 hours prior to use. This will give the paste enough time to come to thermal equilibrium with the environment. The flow rate of paste in a dispensing application depends on viscosity, which can be altered by temperature change. If solder paste is supplied in syringes pre-mixing is not necessary due to the shear action produced from the dispensing.

SOLDER PASTE PRINTING - REFLOW

Best results have been achieved when DSP 718D is re-flowed in a forced air convection oven with a minimum of 8 zones (top & bottom), however, reflow is possible with a 4 zone oven (top & bottom).

The following is a recommended profile for a forced air convection reflow process. The melting temperature of the solder, the heat resistance of the components, and the characteristics of the PCB (i.e. density, thickness, etc.) determine the actual reflow profile.



Preheat Zone - The preheat zone, is also referred to as the ramp zone, and is used to elevate the temperature of the PCB to the desired soak temperature. In the preheat zone the temperature of the PCB is constantly rising, at a rate that should not exceed 2.5 C/sec. The oven's preheat zone should normally occupy 25-33% of the total heated tunnel length.

The Soak Zone - normally occupies 33-50% of the total heated tunnel length exposes the PCB to a relatively steady temperature that will allow the components of different mass to be uniform in temperature. The soak zone also allows the flux to concentrate and the volatiles to escape from the paste.

The Reflow Zone - or spike zone is to elevate the temperature of the PCB assembly from the activation temperature to the recommended peak temperature. The activation temperature is always somewhat below the melting point of the alloy, while the peak temperature is always above the melting point.

CLEANING

DSP 718D is water-soluble formulation, therefore, residue removal is required. Residue removal is easily achieved, with the use of hot 60 °C (140 °F) de-ionized water in either a batch or conveyor cleaner system. Spray pressures should be maintained at 20-30 psi and conveyor speed of 3-6ft/min.

WORKING ENVIRONMENT

Solder paste performs best when used in a controlled environment. Maintaining ambient temperature of between 68-77 F (20-25 C) at a relative humidity of 40-65% will ensure consistent performance and maximum life of paste.

PACKAGING

10cc	35gm
30cc	100gm

DISPOSAL

DSP 718D should be stored in a sealed container and disposed of in accordance with state & local authority requirements.

HEALTH & SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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